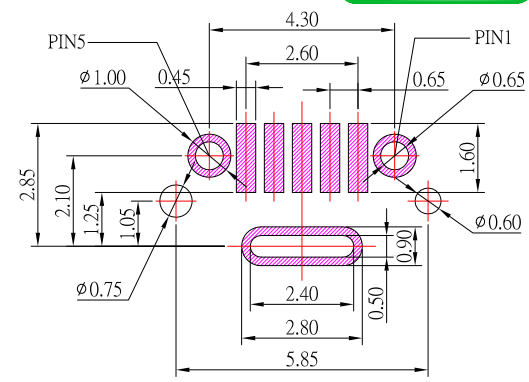
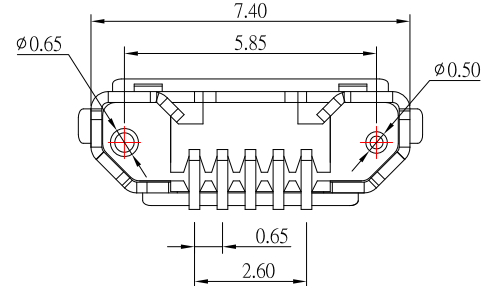




MRUSB-5B-VSE2-x-S165

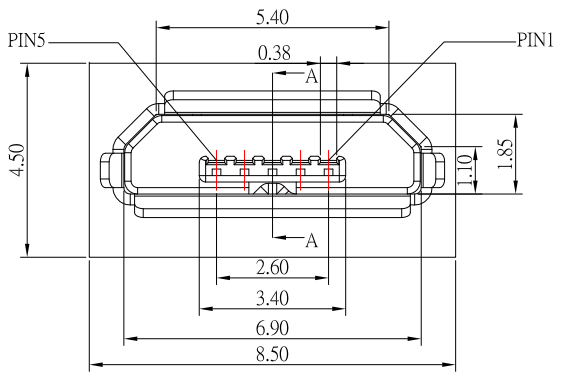
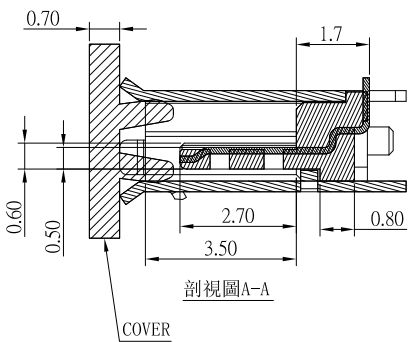
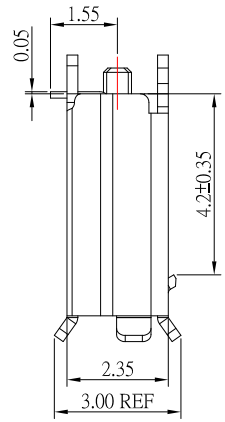
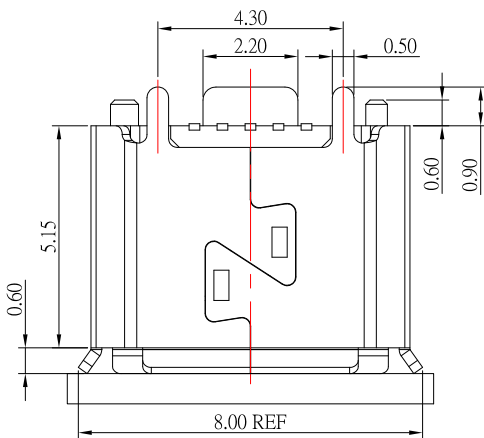
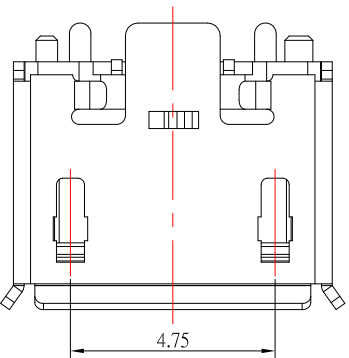
鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"



P.C.B LAYOUT MOUNTING PATTERN

PIN NO.	SIGNAL NAME
PIN 1	VBUS
PIN 2	D-
PIN 3	D+
PIN 4	ID
PIN 5	GND



- NOTES:
- 1.MATERIAL:
- 1.1 HOUSING: LCP,BLACK
- 1.2 CONTACT: PHOSPHOR BRONZE
- 1.3 SHELL: SUS
- 2.Finish:
- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

- 3.SPECIFICATION:
- 3.1 CURRENT RATING: 1.0 A
- 3.2 DIELECTRIC WITHSANDING VOLTAGE: 100 VAC / MINUTE
- 3.3 CONTACT RESISTANCE: 50 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 MATING FORCE: 3.57 KgF MAX.
- 3.6 UNMATING FORCE: 1.0 KgF MIN.
- 3.7 TEMPERATURE RANG : -30°C~80°C

 东莞市高迪电子有限公司
Dong Guan KDRR Electronic Switch Jack Co., Ltd.

TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 ±0.2	3RD. ANGEL'S	UNITS	MM
	Above 5 ~ 15 ±0.3			
	Above 15 ~ 30 ±0.4			
	Above 30 ~ 50 ±0.5			
	Angle ±0.3°			

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	05/04/20	FINISH	MODLE	MICRO USB 直立式 SMT TYPE 有捲邊
CHECKED BY:	DATE	SCALE	DWG NO.	MRUSB-5B-VSE2-x-S165
Jacky Chen	05/04/20	1 : 1	PART NO.	MRUSB-5B-VSE2-x-S165
APPROVED BY:	DATE	SHEET NO.	1 of 1	
Tony Kao	05/04/20			

2	新增鍍層厚度選項	Jack	050420
1	新增PIN定義	Jack	021720
ITEM NO.	DESCRIPTION	DRAWN	DATE